

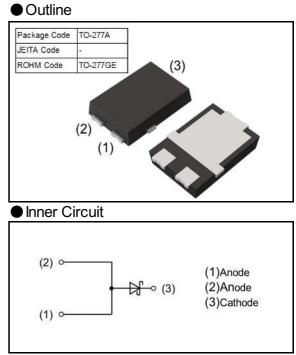
## RBR3RSM40BTF

Schottky Barrier Diode

| V <sub>R</sub> | 40  | V |
|----------------|-----|---|
| lo             | 3   | А |
| IFSM           | 150 | А |

Features
High reliability

Power mold type Low V<sub>F</sub> (AEC-Q101 qualified) Data sheet



#### Packaging Specifications

| <u> </u>         |               |
|------------------|---------------|
| Packing          | Embossed Tape |
| Reel Size(mm)    | 330           |
| Taping Width(mm) | 12            |
| Quantity(pcs)    | 4000          |
| Taping Code      | TL1           |
| Marking          | BR3RSM40B     |
|                  |               |

Application
General rectification

Structure
Silicon epitaxial planar

• Absolute Maximum Ratings ( $T_c=25^{\circ}C$  unless otherwise specified)

| • • •                               |                  |                                                                                                   |           |      |
|-------------------------------------|------------------|---------------------------------------------------------------------------------------------------|-----------|------|
| Parameter                           | Symbol           | Conditions                                                                                        | Limits    | Unit |
| Repetitive peak reverse voltage     | V <sub>RM</sub>  | Duty≦0.5                                                                                          | 40        | V    |
| Reverse voltage                     | V <sub>R</sub>   | Reverse direct voltage                                                                            | 40        | V    |
| Average rectified forward current   | lo               | 60Hz half sin waveform, resistive load,<br>I <sub>o</sub> /2 per diode, T <sub>c</sub> =140°cMax. | 3         | А    |
| Peak forward surge current          | IFSM             | 60Hz half sin waveform,<br>non-repetitive, per diode, T <sub>a</sub> =25°c                        | 150       | А    |
| Junction temperature <sup>(1)</sup> | Тј               | -                                                                                                 | 150       | °C   |
| Storage temperature                 | T <sub>stg</sub> | -                                                                                                 | -55 ~ 150 | °C   |

Note(1) To avoid occurrence of thermal runaway, actual board is to be designed to fulfill  $dP_d/dT_j < 1/R_{\theta JA}$ .

#### Attention

Compared with PN junction diodes, Schottky Barrier Diode is generally high reverse current (IR). The reverse loss of the diode might increase as temperature increasing that causes heat-up and further IR. This phenomenon might end up the thermal destruction(thermal runaway). Therefore please give consideration to the reverse loss and the ambient temperature when using this product.

## • Electrical Characteristics $(T_j=25^{\circ}C \text{ unless otherwise specified})$

| Parameter       | Symbol         | Conditions          | Min. | Тур. | Max. | Unit |
|-----------------|----------------|---------------------|------|------|------|------|
| Forward voltage | VF             | I <sub>F</sub> =3A  | -    | 0.41 | 0.47 | V    |
| Reverse current | l <sub>R</sub> | V <sub>R</sub> =40V | -    | 30   | 120  | μA   |

## Thermal Characteristics

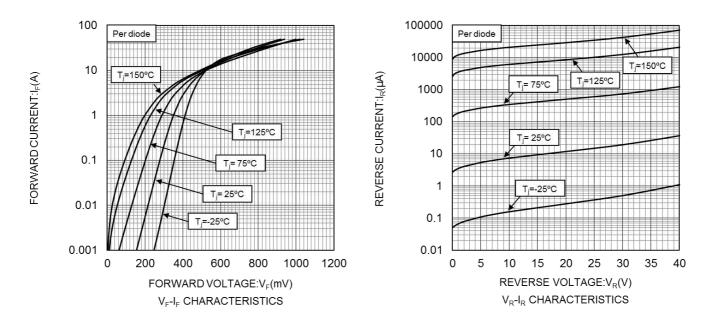
| Parameter                                                   |                  | Min. | Тур. | Max. | Unit |
|-------------------------------------------------------------|------------------|------|------|------|------|
| Thermal Resistance (Junction to case) <sup>(1) (2)</sup>    | R <sub>θJC</sub> | -    | -    | 3.0  | °C/W |
| Thermal Resistance (Junction to ambient) <sup>(1) (3)</sup> |                  | -    | 1    | 90   | °C/W |

注 (1) Value is guaranteed by design.

(2) Transient dual interface measurement (TDIM) method.

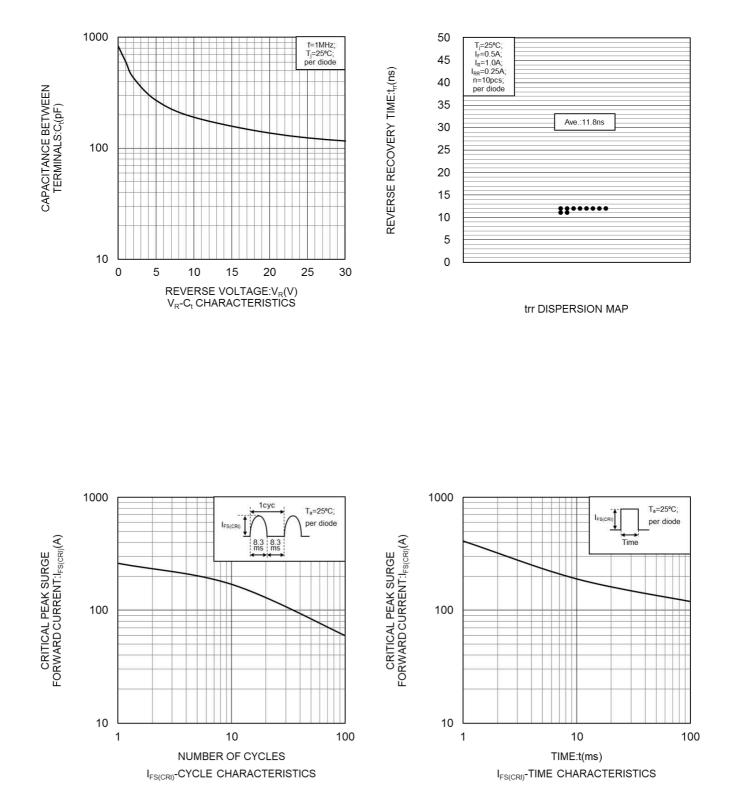
(3) Mounted on 50 x 50 x 1.6mm FR4 board, single-sided copper, 35µm thickness, reference footprint.

## Characteristic Curves





### Characteristic Curves





## Characteristic Curves

I. --

Half sine wave

1

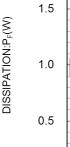
2

t→ T D=t/T

D=0.5

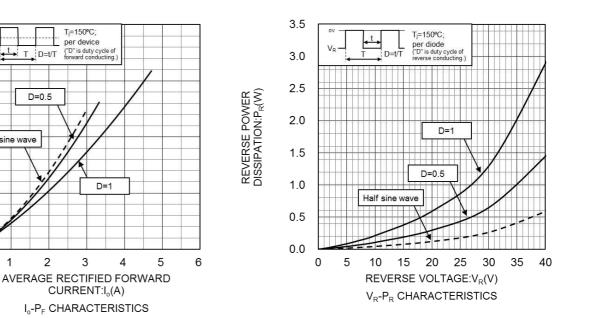
2.0

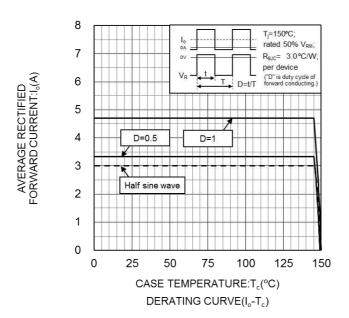




0.0

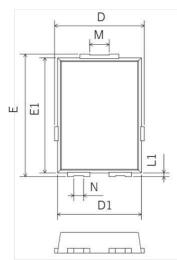
0

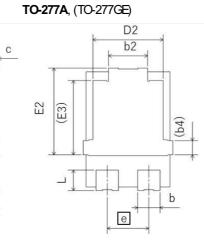


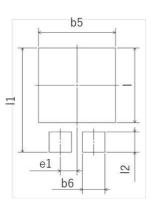




## Dimensions







Reference pattern of soldering pads

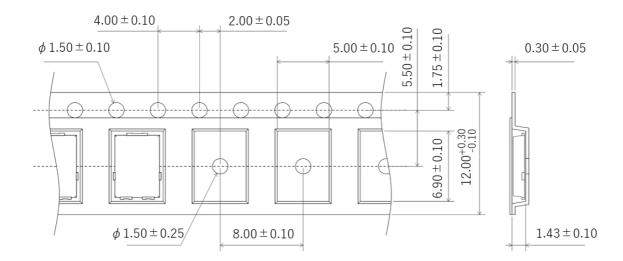
Inches Typ. 0.189 0.055 0.041 0.186 0.268 0.050

| DIM |      | Inches |       |       | Milimeters |      |   |
|-----|------|--------|-------|-------|------------|------|---|
| DIN | Min. | Max.   | Min.  | Max.  | DIM        | Typ. | Γ |
| А   | 1.00 | 1.20   | 0.039 | 0.047 | b5         | 4.80 | T |
| b   | 1.05 | 1.35   | 0.041 | 0.053 | b6         | 1.40 | 1 |
| b2  | 1.90 | 2.20   | 0.075 | 0.087 | e1         | 1.04 | + |
| b4  | 0.   | 75     | 0.0   | 30    | ei         |      | ╈ |
| с   | 0.15 | 0.40   | 0.006 | 0.016 |            | 4.72 | + |
| D   | 4.45 | 4.75   | 0.175 | 0.187 | 1          | 6.80 |   |
| D1  | 4.25 | 4.35   | 0.167 | 0.171 | 12         | 1.27 |   |
| D2  | 3.40 | 3.70   | 0.134 | 0.146 | 1          |      |   |
| E   | 6.35 | 6.65   | 0.250 | 0.262 | 1          |      |   |
| E1  | 6.05 | 6.15   | 0.238 | 0.242 | 1          |      |   |
| E2  | 4.40 | 4.80   | 0.173 | 0.189 | 1          |      |   |
| E3  | 3.   | 94     | 0.1   | 55    |            |      |   |
| е   | 2.   | 13     | 0.0   | 84    | 1          |      |   |
| L   | 0.94 | 1.24   | 0.037 | 0.049 | 1          |      |   |
| L1  | 0.05 | 0.35   | 0.002 | 0.014 |            |      |   |
| М   | 0.65 | 1.15   | 0.026 | 0.045 | 7          |      |   |
| N   | 0.25 | 0.75   | 0.010 | 0.030 | 1          |      |   |

T

А

## ● Taping (Unit:mm)





# Notice

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| (Note1) Medical Equipment Classification of the Specific Applications |
|-----------------------------------------------------------------------|
|-----------------------------------------------------------------------|

| JAPAN   | USA     | EU         | CHINA   |
|---------|---------|------------|---------|
| CLASSII | CLASSI  | CLASS II b | CLASSⅢ  |
| CLASSIV | CLASSII | CLASSⅢ     | CLASSII |

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  - [a] Use of our Products in any types of liquid, including water, oils, chemicals, and organic solvents
  - [b] Use of our Products outdoors or in places where the Products are exposed to direct sunlight or dust
  - [c] Use of our Products in places where the Products are exposed to sea wind or corrosive gases, including Cl<sub>2</sub>, H<sub>2</sub>S, NH<sub>3</sub>, SO<sub>2</sub>, and NO<sub>2</sub>
  - [d] Use of our Products in places where the Products are exposed to static electricity or electromagnetic waves
  - [e] Use of our Products in proximity to heat-producing components, plastic cords, or other flammable items
  - [f] Sealing or coating our Products with resin or other coating materials
  - [g] Use of our Products without cleaning residue of flux (Exclude cases where no-clean type fluxes is used. However, recommend sufficiently about the residue.); or Washing our Products by using water or water-soluble cleaning agents for cleaning residue after soldering
  - [h] Use of the Products in places subject to dew condensation
- 4. The Products are not subject to radiation-proof design.
- 5. Please verify and confirm characteristics of the final or mounted products in using the Products.
- 6. In particular, if a transient load (a large amount of load applied in a short period of time, such as pulse, is applied, confirmation of performance characteristics after on-board mounting is strongly recommended. Avoid applying power exceeding normal rated power; exceeding the power rating under steady-state loading condition may negatively affect product performance and reliability.
- 7. De-rate Power Dissipation depending on ambient temperature. When used in sealed area, confirm that it is the use in the range that does not exceed the maximum junction temperature.
- 8. Confirm that operation temperature is within the specified range described in the product specification.
- 9. ROHM shall not be in any way responsible or liable for failure induced under deviant condition from what is defined in this document.

#### Precaution for Mounting / Circuit board design

- 1. When a highly active halogenous (chlorine, bromine, etc.) flux is used, the residue of flux may negatively affect product performance and reliability.
- 2. In principle, the reflow soldering method must be used on a surface-mount products, the flow soldering method must be used on a through hole mount products. If the flow soldering method is preferred on a surface-mount products, please consult with the ROHM representative in advance.

For details, please refer to ROHM Mounting specification

#### Precautions Regarding Application Examples and External Circuits

- 1. If change is made to the constant of an external circuit, please allow a sufficient margin considering variations of the characteristics of the Products and external components, including transient characteristics, as well as static characteristics.
- 2. You agree that application notes, reference designs, and associated data and information contained in this document are presented only as guidance for Products use. Therefore, in case you use such information, you are solely responsible for it and you must exercise your own independent verification and judgment in the use of such information contained in this document. ROHM shall not be in any way responsible or liable for any damages, expenses or losses incurred by you or third parties arising from the use of such information.

#### **Precaution for Electrostatic**

This Product is electrostatic sensitive product, which may be damaged due to electrostatic discharge. Please take proper caution in your manufacturing process and storage so that voltage exceeding the Products maximum rating will not be applied to Products. Please take special care under dry condition (e.g. Grounding of human body / equipment / solder iron, isolation from charged objects, setting of lonizer, friction prevention and temperature / humidity control).

#### Precaution for Storage / Transportation

- 1. Product performance and soldered connections may deteriorate if the Products are stored in the places where:
  - [a] the Products are exposed to sea winds or corrosive gases, including Cl<sub>2</sub>, H<sub>2</sub>S, NH<sub>3</sub>, SO<sub>2</sub>, and NO<sub>2</sub>
  - [b] the temperature or humidity exceeds those recommended by ROHM
  - [c] the Products are exposed to direct sunshine or condensation
  - [d] the Products are exposed to high Electrostatic
- 2. Even under ROHM recommended storage condition, solderability of products out of recommended storage time period may be degraded. It is strongly recommended to confirm solderability before using Products of which storage time is exceeding the recommended storage time period.
- 3. Store / transport cartons in the correct direction, which is indicated on a carton with a symbol. Otherwise bent leads may occur due to excessive stress applied when dropping of a carton.
- 4. Use Products within the specified time after opening a humidity barrier bag. Baking is required before using Products of which storage time is exceeding the recommended storage time period.

#### **Precaution for Product Label**

A two-dimensional barcode printed on ROHM Products label is for ROHM's internal use only.

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When disposing Products please dispose them properly using an authorized industry waste company.

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